

## SCANSTA476 Eight Input IEEE 1149.1 Analog Voltage Monitor

Check for Samples: [SCANSTA476](#)

### FEATURES

- Eight Selectable Analog Input Channels
- Analog Full-Scale Input Range 0V to  $V_{DD}$
- Typical Accuracy of 2 mV at Maximum  $V_{DD}$
- Very Low Power Operation
- Small Package Footprint in 16-Lead, 5 x 5 x 0.8 mm WSON
- Single +2.7V to +5.5V Supply Operation
- IEEE 1149.1 (JTAG) Compliant Interface

### APPLICATIONS

- Measurement of Point Voltages
- Real-time Signal Monitoring
- System Health Monitoring and Prognostics
- Debug, Environmental Test, Production Test, Field Service
- Supplement In-Circuit Tester (ICT) Access
- Vital in Servers, Computing, Telecommunication and Industrial Equipment
- Essential in Medical, Data Storage, and Networking Equipment

### DESCRIPTION

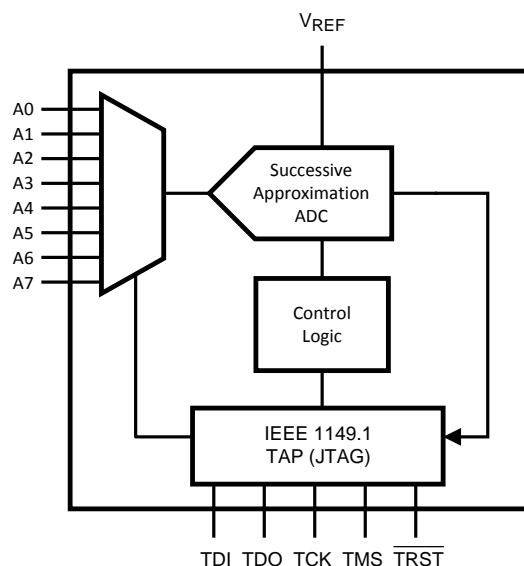
The SCANSTA476 is a low power, Analog Voltage Monitor used for sampling or monitoring up to 8 analog/mixed-signal input channels. Analog Voltage Monitors are valuable during product development, environmental test, production, and field service for verifying and monitoring power supply and reference voltages. In a supervisory role, the 'STA476 is useful for card or system-level health monitoring and prognostics applications.

Instead of requiring an external microcontroller with a GPIO interface, the 'STA476 features a common IEEE 1149.1 (JTAG) interface to select the analog input, initiate a measurement, and access the results - further extending the capabilities of an existing JTAG infrastructure.

The SCANSTA476 uses the  $V_{REF}$  input as a reference. This enables the SCANSTA476 to operate with a full-scale input range of 0 to  $V_{DD}$ , which can range from +2.7V to +5.5V.

The SCANSTA476 is packaged in a 16-lead non-pullback WSON package that provides an extremely small footprint for applications where space is a critical consideration. This product operates over the industrial temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ .

### Block Diagram



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Connection Diagram

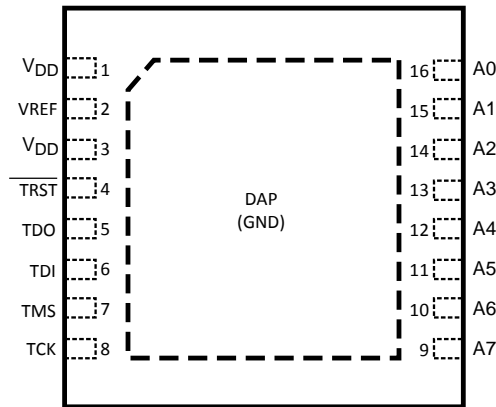


Figure 1. DAP = GND (Top View)

Pin Descriptions

| Pin No.             | Symbol            | Description  |
|---------------------|-------------------|--|
| <b>ANALOG I/O</b>   |                   |  |
| 16                  | A0                | Analog input 0. This signal can range from 0V to $V_{REF}$ .   |
| 15                  | A1                | Analog input 1. This signal can range from 0V to $V_{REF}$ .   |
| 14                  | A2                | Analog input 2. This signal can range from 0V to $V_{REF}$ .   |
| 13                  | A3                | Analog input 3. This signal can range from 0V to $V_{REF}$ .   |
| 12                  | A4                | Analog input 4. This signal can range from 0V to $V_{REF}$ .   |
| 11                  | A5                | Analog input 5. This signal can range from 0V to $V_{REF}$ .   |
| 10                  | A6                | Analog input 6. This signal can range from 0V to $V_{REF}$ .   |
| 9                   | A7                | Analog input 7. This signal can range from 0V to $V_{REF}$ .   |
| 2                   | $V_{REF}$         | Analog reference voltage input. $V_{REF}$ must be $\leq V_{DD}$ . This pin should be connected to a quiet source (not directly to $V_{DD}$ ) and bypassed to GND with 0.1 $\mu$ F and 1 $\mu$ F monolithic capacitors located within 1 cm of the $V_{REF}$ pin.                      |
| <b>DIGITAL I/O</b>  |                   |  |
| 6                   | TDI               | Test Data Input to support IEEE 1149.1 features  |
| 5                   | TDO               | Test Data Output to support IEEE 1149.1 features   |
| 7                   | TMS               | Test Mode Select to support IEEE 1149.1 features   |
| 8                   | TCK               | Test Clock to support IEEE 1149.1 features   |
| 4                   | $\overline{TRST}$ | Test Reset to support IEEE 1149.1 features   |
| <b>POWER SUPPLY</b> |                   |  |
| 1,3                 | $V_{DD}$          | Positive supply pin. These pins should be connected to a quiet +2.7V to +5.5V source and bypassed to GND with 0.1 $\mu$ F and 1 $\mu$ F monolithic capacitors located within 1 cm of the power pin.  |
| See <sup>(1)</sup>  | GND               | Ground reference for CMOS circuitry. DAP is the exposed metal contact at the bottom of the WSON package. The DAP is used as the primary GND connection to the device. It should be connected to the ground plane with at least 4 vias for optimal low-noise and thermal performance. |

(1) Note that GND is not an actual pin on the package, the GND is connected thru the DAP on the back side of the WSON package.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Absolute Maximum Ratings <sup>(1)(2)</sup>

|   |                  |  |
|---|------------------|--|
| Supply Voltage $V_{DD}$                 |                  | -0.3V to +6.5V                               |
| Voltage on Any Analog Pin to GND        |                  | -0.3V to $V_{DD}+0.3V$                       |
| Voltage on Any Digital Pin to GND       |                  | -0.3V to $V_{DD}+0.3V$                       |
| Input Current at Any Pin <sup>(3)</sup> |                  | ±10 mA                                       |
| ESD Susceptibility                      | Human Body Model | 8000V  |
|   | Machine Model    | >250V  |
| Soldering Temperature                   |                  | Refer to AN-1187 ( <a href="#">SNOA401</a> ) |
| Junction Temperature                    |                  | +150°C                                       |
| Storage Temperature                     |                  | -65°C to +150°C                              |
| Thermal Resistance, $\theta_{JA}$       |                  | 42°C/W                                       |
| Thermal Resistance, $\theta_{JC}$       |                  | 14.3°C/W                                     |

- (1) Absolute maximum ratings are limiting values, to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not implied. Exposure to maximum ratings for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) Except power supply pins.

### Recommended Operating Conditions

|  |   |
|--|---|
| Operating Temperature Range                    | $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ |
| $V_{DD}$ Supply Voltage                        | +2.7V to +5.5V  |
| Digital Input Pins Voltage Range               | +0V to $V_{DD}$   |
| Analog Input Pins Voltage Range <sup>(1)</sup> | +0V to $V_{REF}$  |

- (1) For valid measurements, the analog  $V_{IN} < V_{REF} \leq V_{DD}$ .

### SCANSTA476 Electrical Characteristics

The following specifications apply for  $V_{DD} = +2.7V$  to 5.5V,  $f_{TCK} = 20$  MHz, unless otherwise noted.

| Symbol   | Parameter                                    | Conditions   | Typical | Limits         | Units    |
|--|--|--|---------|----------------|----------|
| <b>POWER SUPPLY CHARACTERISTICS</b>                        |  |  |         |                |          |
| $V_{DD}$   | Supply Voltage                               | $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ |         | 2.7            | V (min)  |
|  |  |  |         | 5.5            | V (max)  |
| $I_{DD}$   | Normal Mode (Static)                         | $V_{DD} = +2.7V$ to +5.5V,                             | 3.5     | 5.0            | mA       |
|  | Normal Mode (Operational)                    | $V_{DD} = +2.7V$ to +5.5V,<br>$f_{TCK} = 1$ MSPS       |         |                |          |
| $P_D$  | Power Consumption, Normal Mode (Operational) | $V_{DD} = +5.5V$ , $f_{TCK} = 1$ MSPS                  |         | 27.5           | mW (max) |
| <b>ANALOG INPUT CHARACTERISTICS (A0-A7)</b>                |  |  |         |                |          |
| $V_{IN}$   | Analog Input Range                           | $V_{REF} \leq V_{DD}$                                  |         | 0 to $V_{REF}$ | V        |
| $V_{REF}$  | Reference Voltage Range                      |  |         | $V_{DD}$       | V        |
| $I_{DCL}$  | DC Leakage Current                           |  | 0.1     | ±10            | µA (max) |
| $V_{MEAS}$   | Analog Input Measurement Accuracy            | $V_{DD} = +2.7V$                                       | 1       | 7.5            | mV       |
|  |  | $V_{DD} = +5.5V$                                       | 2       | 15             |          |
| <b>DIGITAL INPUT CHARACTERISTICS (TDI, TMS, TCK, TRST)</b> |  |  |         |                |          |
| $V_{IH}$   | Input High Voltage                           | $V_{DD} = +2.7V$ to +3.6V                              |         | 2.0            | V (min)  |
|  |  | $V_{DD} = +5.5V$                                       |         | 2.1            |          |
| $V_{IL}$   | Input Low Voltage                            | $V_{DD} = +5V$   |         | 0.8            | V (max)  |
| $V_{CL}$   | Input Clamp Voltage                          | $I_{CL} = -18mA$                                       | -0.8    | -1.5           | V (max)  |
| $I_{IN}$   | Input Current                                | $V_{IN} = 0V$ or $V_{DD}$                              | 0.2     | ±10            | µA (max) |

## SCANSTA476 Electrical Characteristics (continued)

The following specifications apply for  $V_{DD} = +2.7V$  to  $5.5V$ ,  $f_{TCK} = 20$  MHz, unless otherwise noted.

| Symbol                                      | Parameter                              | Conditions  | Typical                   | Limits         | Units         |
|---|--|---|---------------------------|----------------|---------------|
| $I_{ILR}$                                   | Input Current                          | $\overline{TRST}$ , TDI, TMS only                 |                           | -300           | $\mu A$ (max) |
| <b>DIGITAL OUTPUT CHARACTERISTICS (TDO)</b> |  |   |                           |                |               |
| $V_{OH}$                                    | Output High Voltage                    | $I_{OH} = -100 \mu A, 2.7V \leq V_{DD} \leq 5.5V$ |                           | $V_{DD} - 0.2$ | V (min)       |
|   |  | $I_{OH} = -4 mA, 3.0V \leq V_{DD} \leq 5.5V$      |                           | 2.4            | V (min)       |
|   |  | $I_{OH} = -4 mA, V_{DD} = 2.7V$                   |                           | 2.2            | V (min)       |
| $V_{OL}$                                    | Output Low Voltage                     | $I_{OL} = 100 \mu A, 2.7V \leq V_{DD} \leq 5.5V$  |                           | 0.2            | V (max)       |
|   |  | $I_{OL} = 4 mA, 2.7V \leq V_{DD} \leq 5.5V$       |                           | 0.4            | V (max)       |
| $I_{OS}$                                    | Output Short Circuit Current           | $V_{OUT} = 0V, V_{DD} = 5.5V$                     |                           | -85            | mA (max)      |
| $I_{OZ}$                                    | TRI-STATE Leakage Current              |   |                           | $\pm 10$       | $\mu A$ (max) |
|   | Output Coding                          |   | Straight (Natural) Binary |                |               |
| <b>AC ELECTRICAL CHARACTERISTICS</b>        |  |   |                           |                |               |
| $F_{MAX}$                                   | Throughput Rate                        | TCK = 20MHz                                       |                           | 1              | MSPS (max)    |
| <b>INPUT TIMING CHARACTERISTICS</b>         |  |   |                           |                |               |
| $t_{SET}$                                   | TDI to TCK (H/L)                       | See <sup>(1)</sup>                                |                           | 2.0            | ns (min)      |
| $t_{HOLD}$                                  | TDI to TCK (H/L)                       | See <sup>(1)</sup>                                |                           | 1.5            | ns (min)      |
| $t_{SET}$                                   | TMS to TCK (H/L)                       | See <sup>(1)</sup>                                |                           | 2.0            | ns (min)      |
| $t_{HOLD}$                                  | TMS to TCK (H/L)                       | See <sup>(1)</sup>                                |                           | 2.0            | ns (min)      |
| $t_W$                                       | TCK Pulse Width (H/L)                  | See <sup>(1)</sup>                                |                           | 10.0           | ns (min)      |
| $t_{REC}$                                   | Recovery Time $\overline{TRST}$ to TCK | See <sup>(1)</sup>                                |                           | 2.0            | ns (min)      |
| $t_W$                                       | TRST Pulse Width (L)                   | See <sup>(1)</sup>                                |                           | 2.5            | ns (min)      |
| $F_{MAX}$                                   | TCK                                    |   |                           | 20             | MHz (min)     |

(1) Data sheet min/max specification limits are specified by design or statistical analysis.

## APPLICATIONS INFORMATION

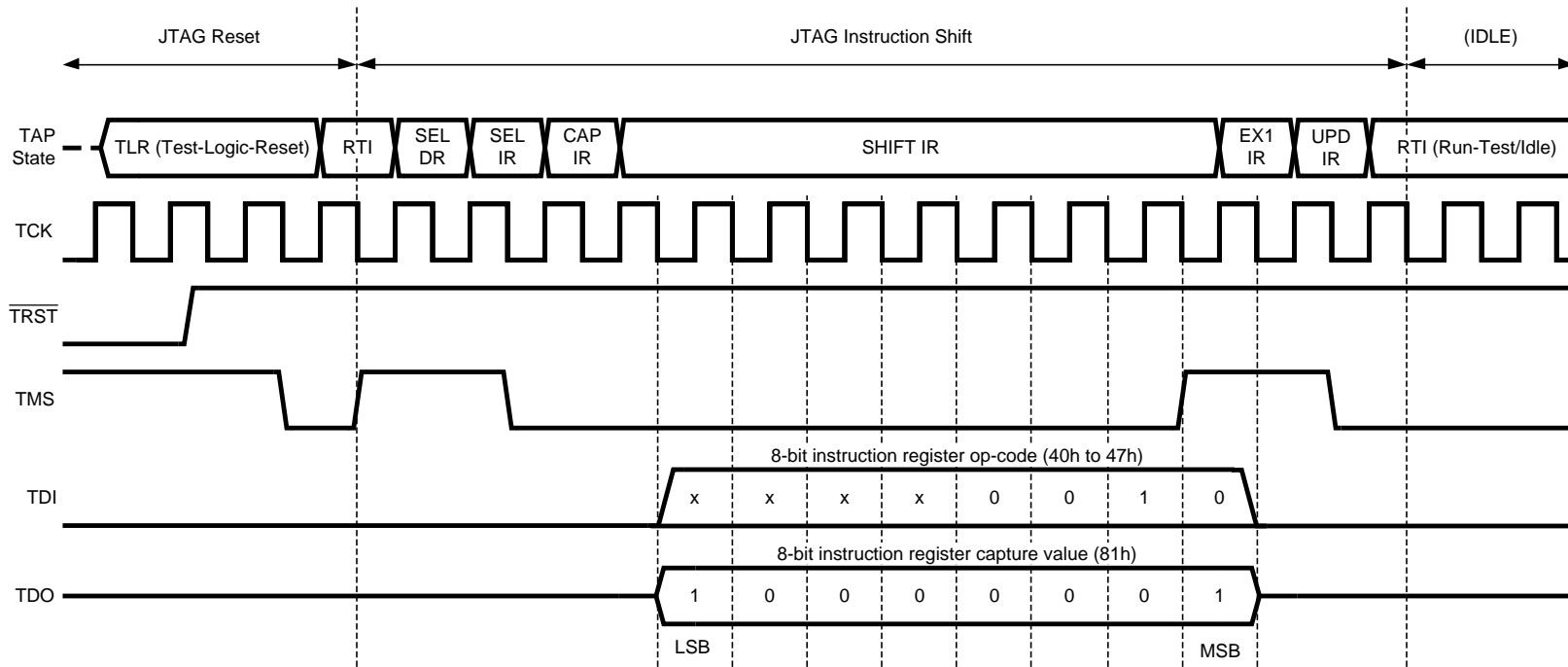
### POWER-UP TIMING

The SCANSTA476 typically requires 1  $\mu s$  to power up, either after first applying  $V_{DD}$ , or after an incomplete conversion shift. To return to normal, one "dummy" conversion must be fully completed. After this first dummy conversion, the SCANSTA476 will perform conversions properly.

### STARTUP MODE

When the  $V_{DD}$  supply is first applied, the SCANSTA476 requires one dummy conversion after start-up.

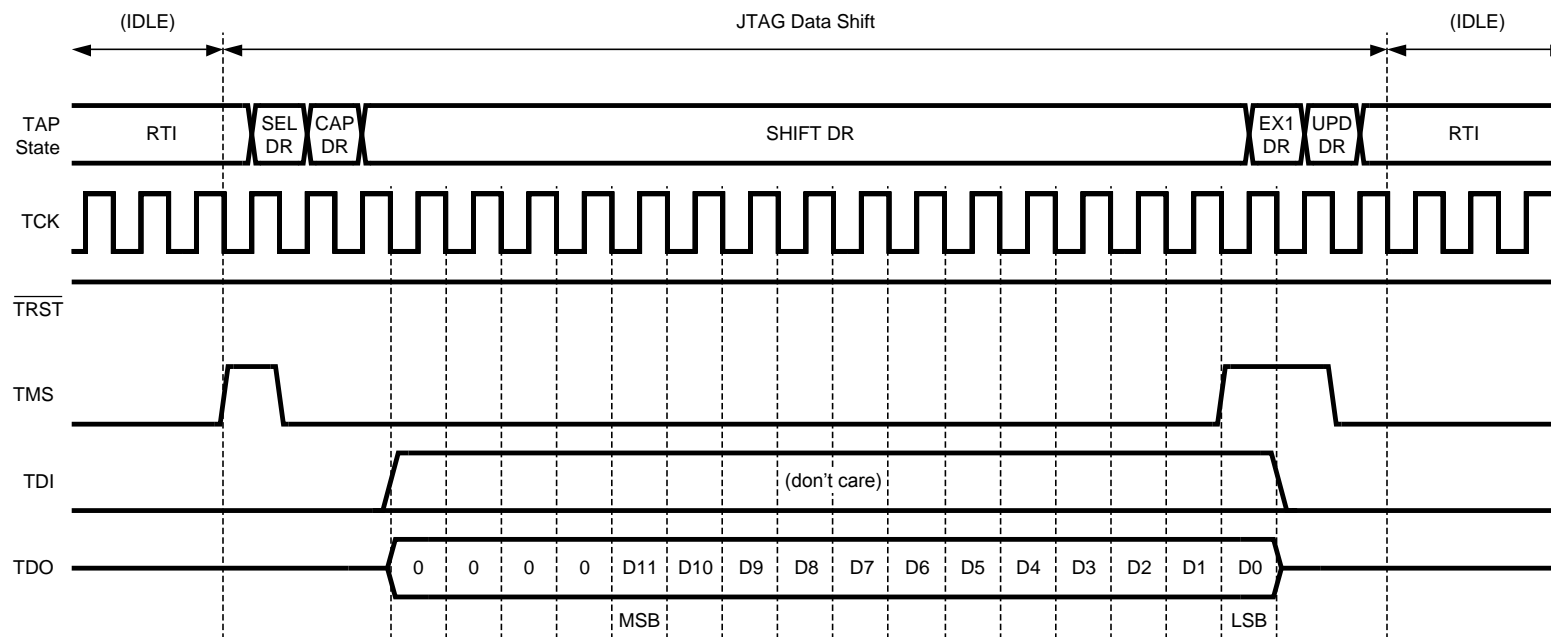
Timing Diagrams



Op-codes 40h to 47h select pins A0 to A7 respectively.

Note the JTAG reset preamble places the JTAG TAP controller in a stable state (RTI). Both the instruction and data shifts start in - and return to - the RTI state

Figure 2. Instruction Shift (Channel Select)



D11 through D0 correspond to the 12-bit sample from the ADC Core.

Note that Data shifts can be run back-to-back for continuous sampling of a single channel, or can be interleaved with instruction shifts for rippling through all 8 channels.

**Figure 3. Data Shift (A/D Sample)**

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**REVISION HISTORY**

| <b>Changes from Revision F (April 2013) to Revision G</b>  | <b>Page</b>       |
|--|-------------------|
| <ul style="list-style-type: none"><li>• Changed layout of National Data Sheet to TI format .....</li></ul> | <a href="#">6</a> |

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**PACKAGING INFORMATION**

| Orderable Device   | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2)         | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|-------------------------|---------|
| SCANSTA476TSD/NOPB | ACTIVE        | WSON         | NHQ             | 16   | 1000        | Green (RoHS & no Sb/Br) | CU SN            | Level-3-260C-168 HR  | -40 to 85    | STA476T                 | Samples |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

| Device             | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SCANSTA476TSD/NOPB | WSON         | NHQ             | 16   | 1000 | 178.0              | 12.4               | 5.3     | 5.3     | 1.3     | 8.0     | 12.0   | Q1            |

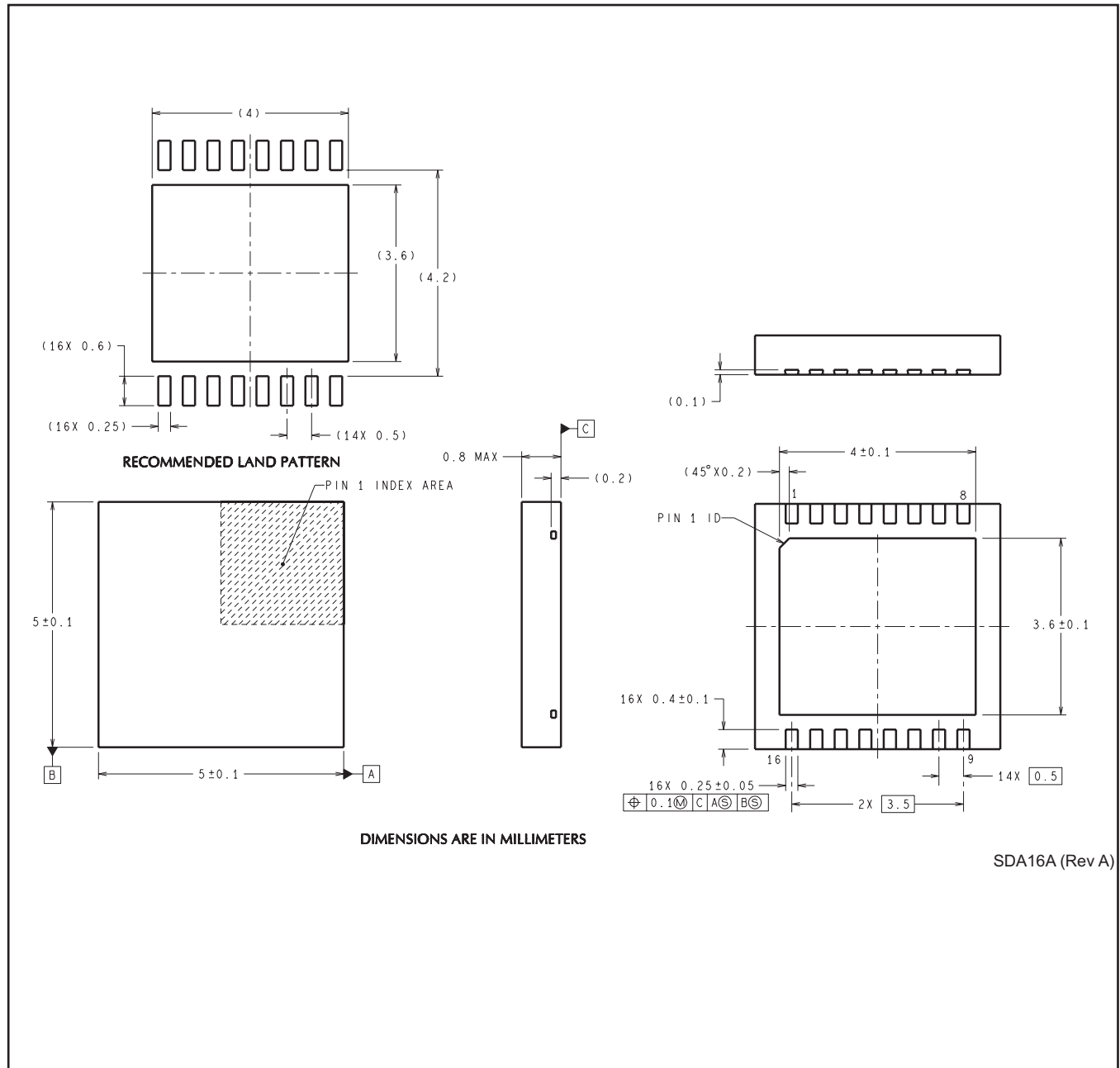
**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

| Device             | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SCANSTA476TSD/NOPB | WSON         | NHQ             | 16   | 1000 | 213.0       | 191.0      | 55.0        |

NHQ0016A



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